

FIG. 1

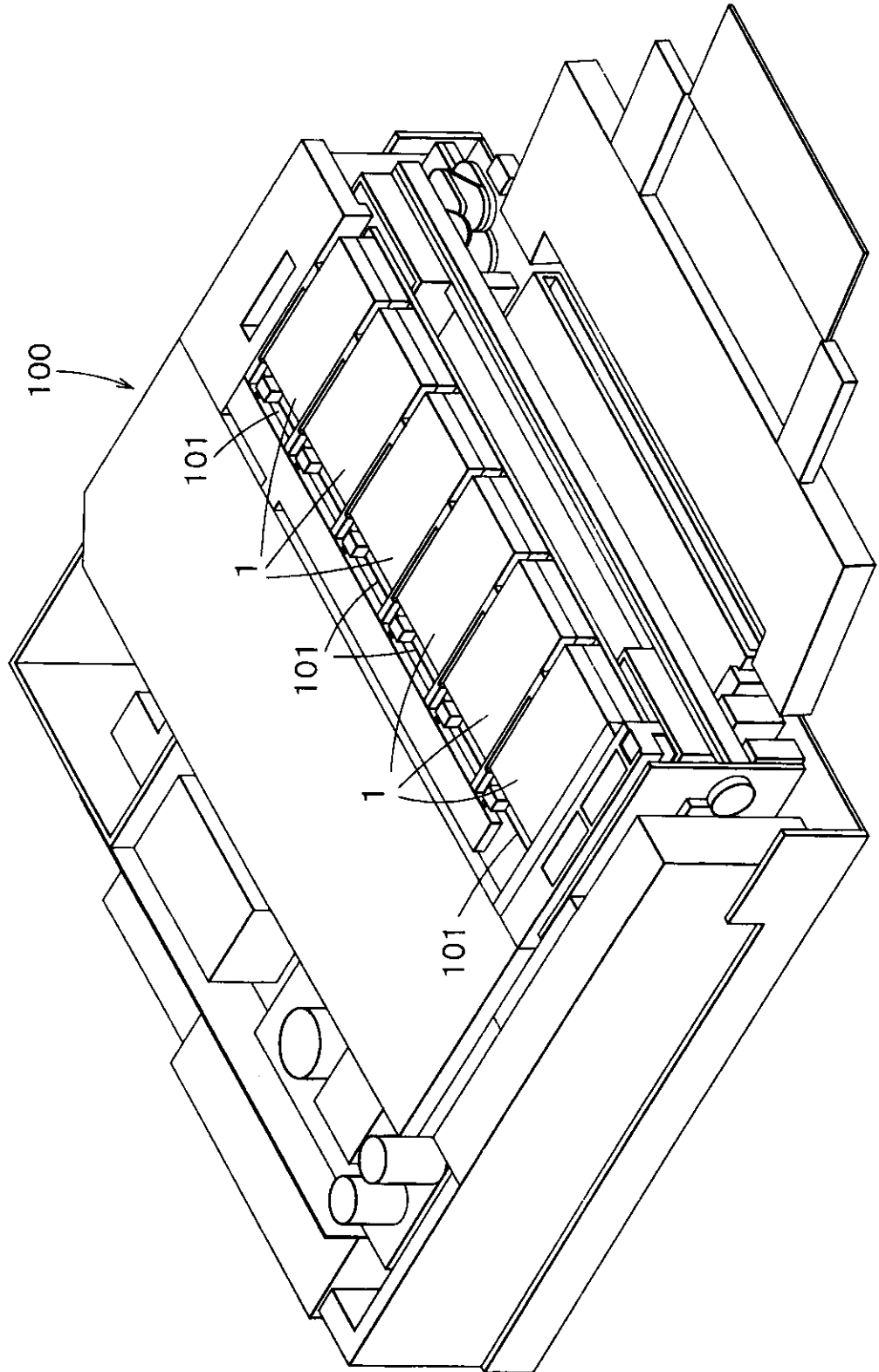


FIG. 2C

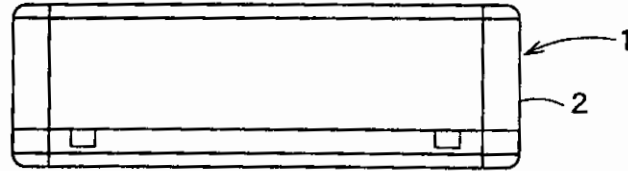


FIG. 2B

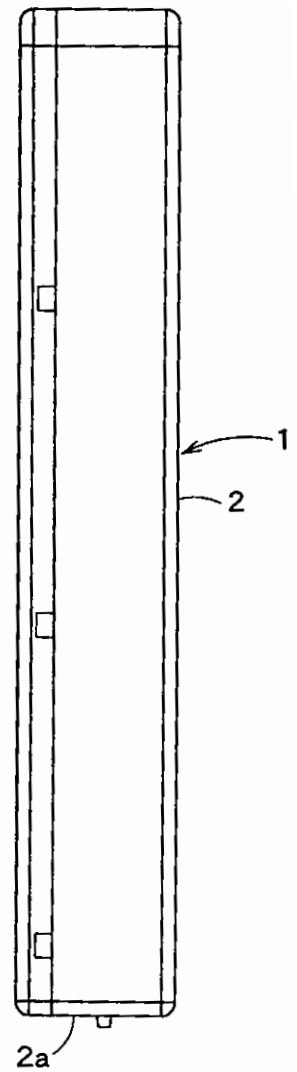


FIG. 2A

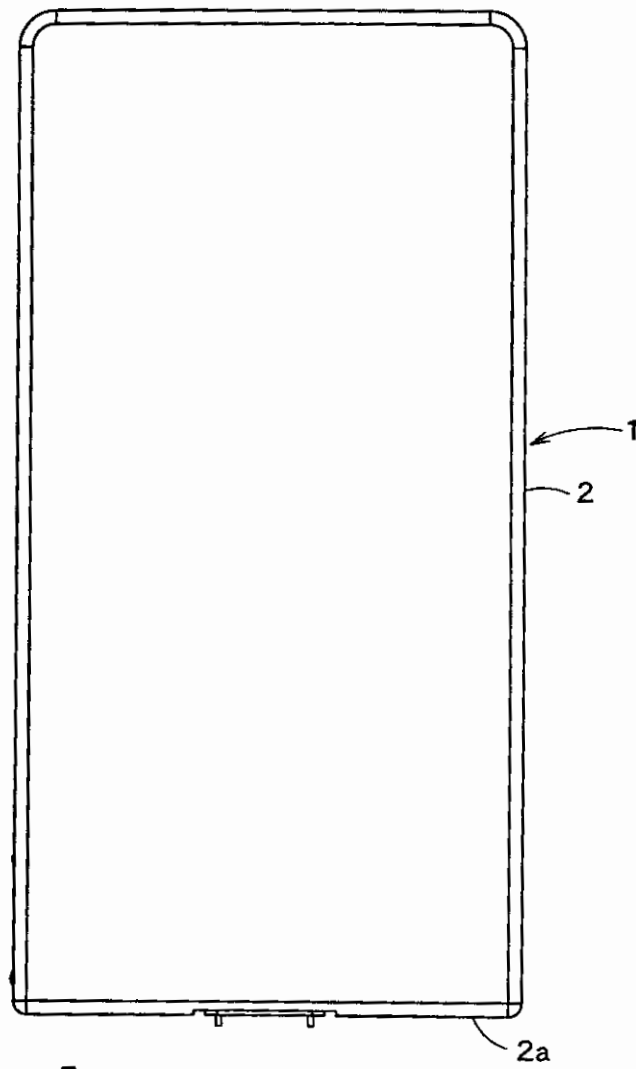


FIG. 2D

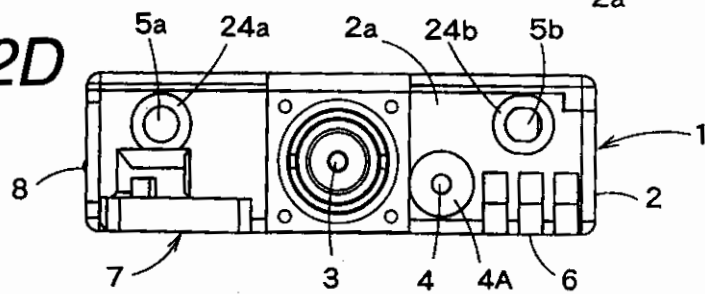


FIG. 3A

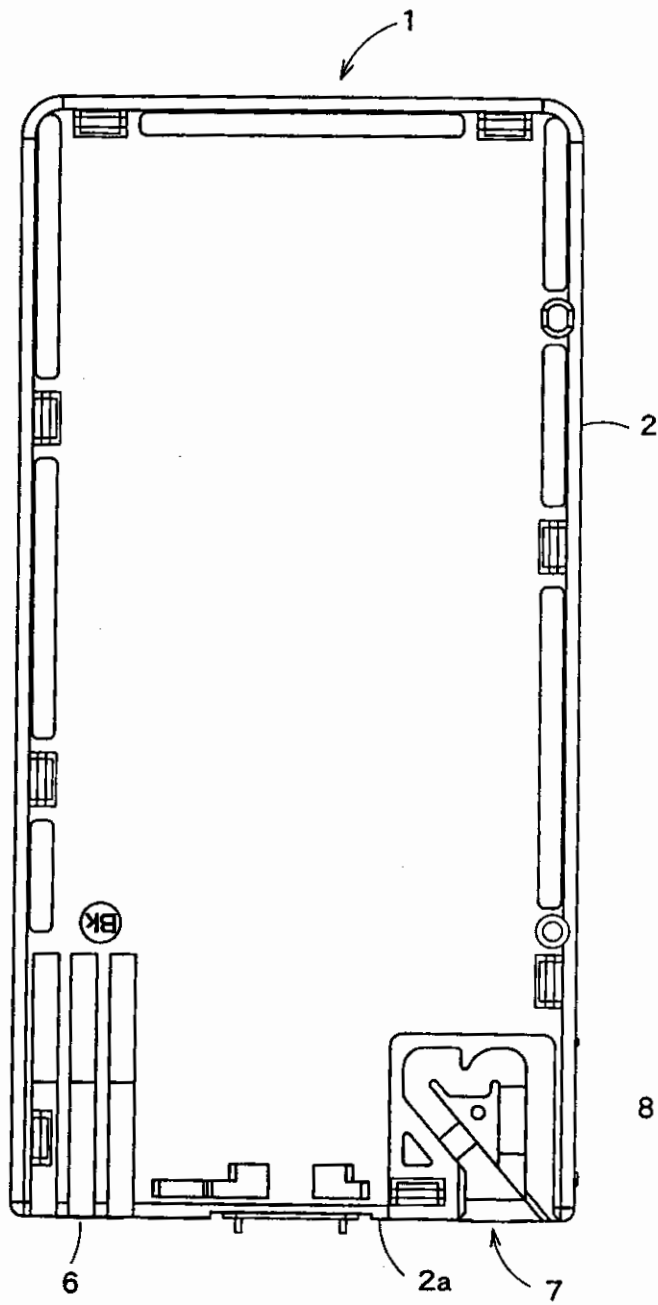


FIG. 3B

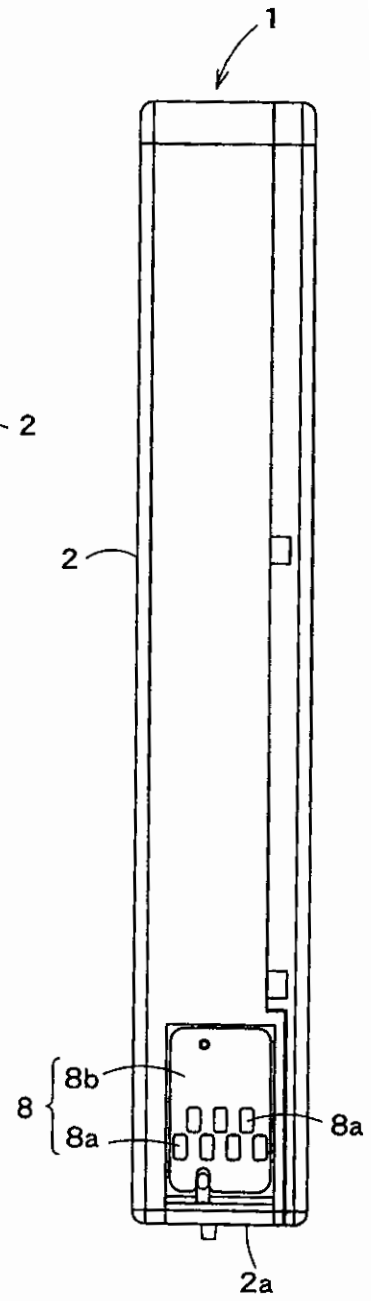


FIG. 4A

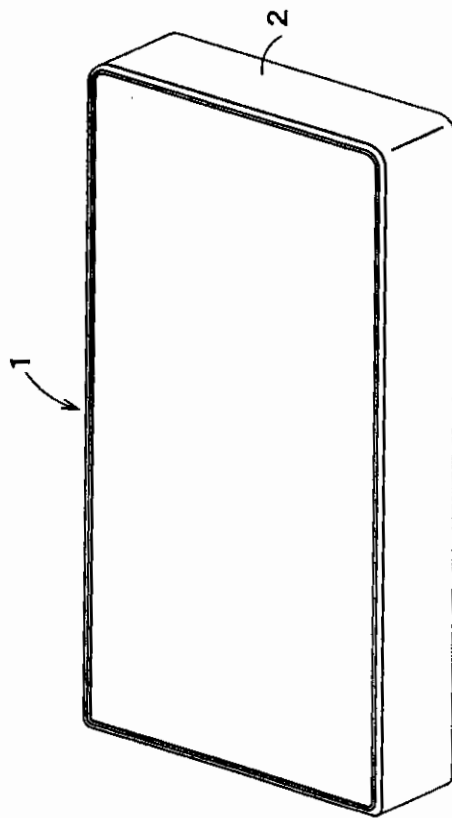


FIG. 4B

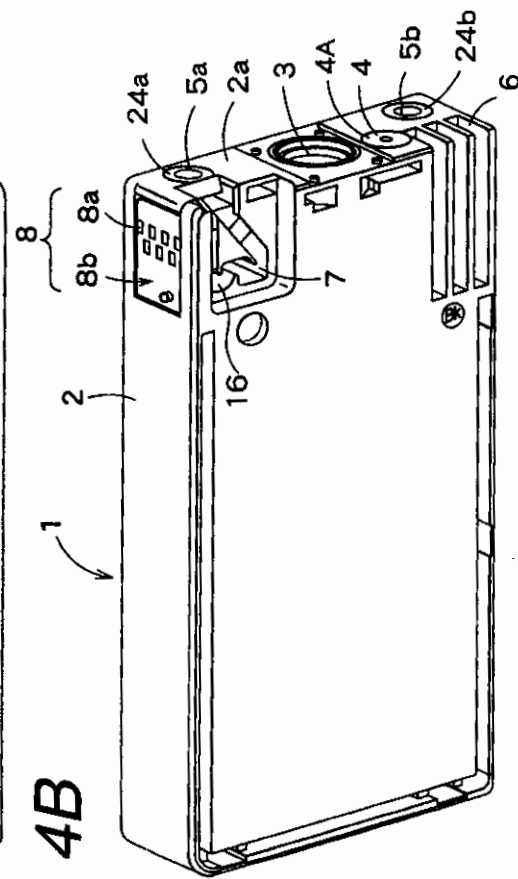


FIG. 4C

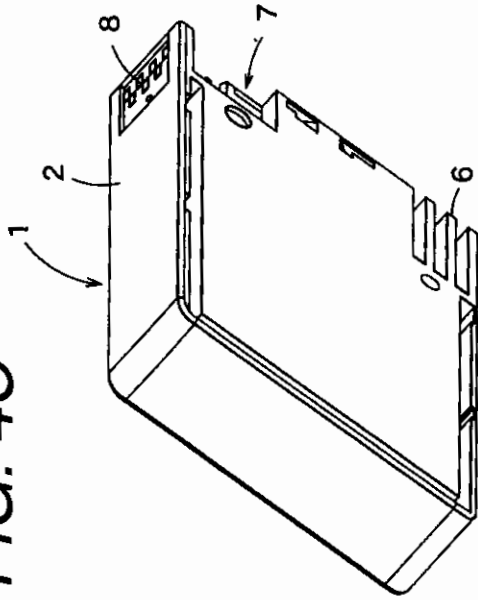


FIG. 4D

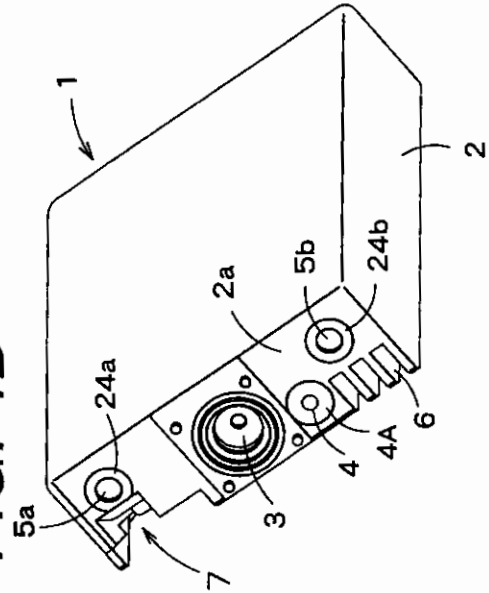


FIG. 5

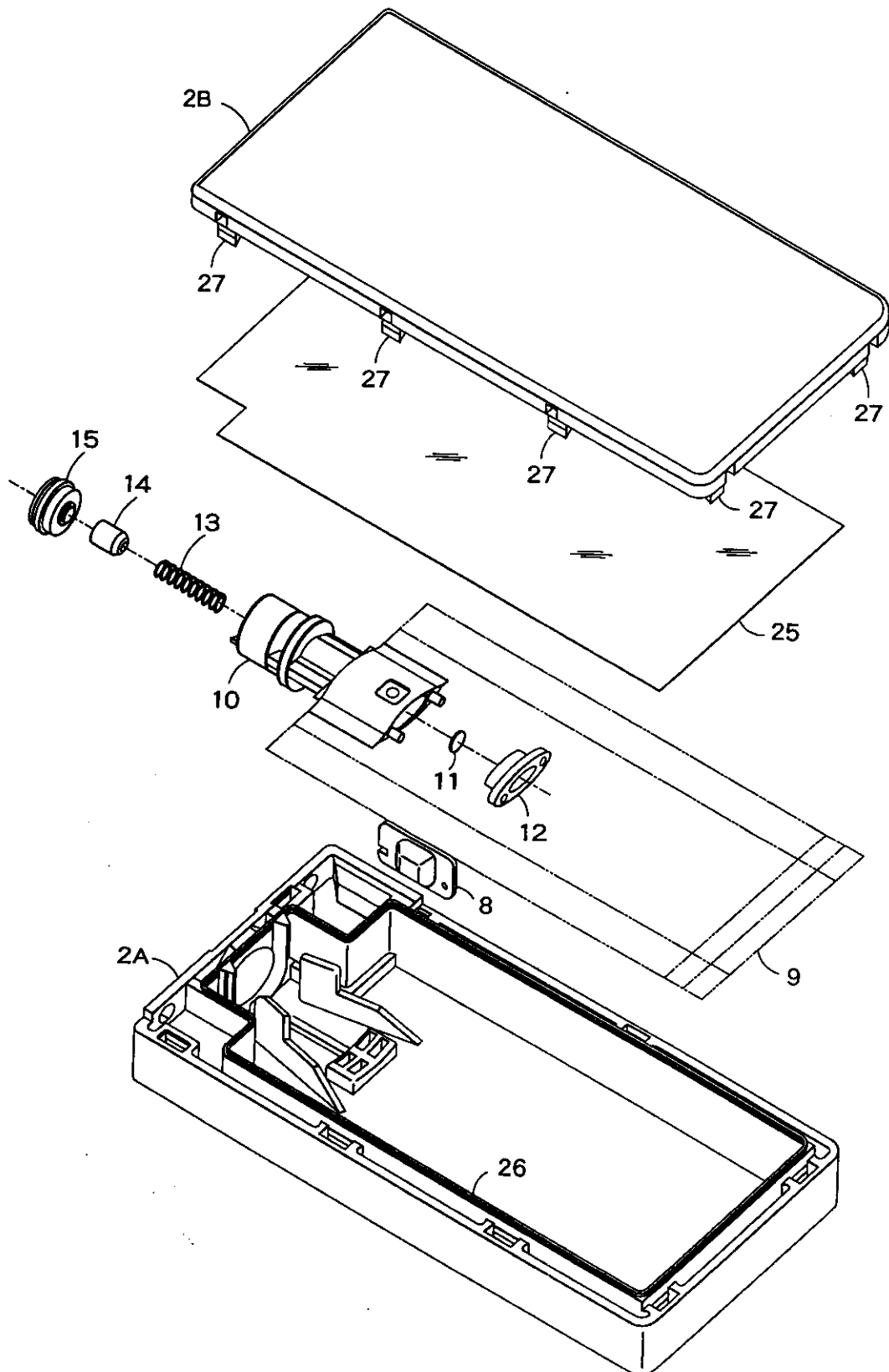


FIG. 6B

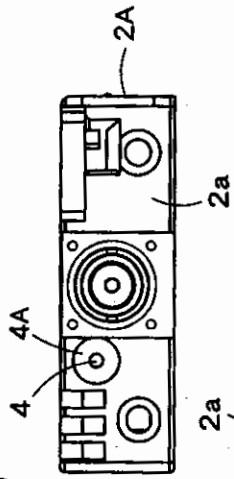


FIG. 6D

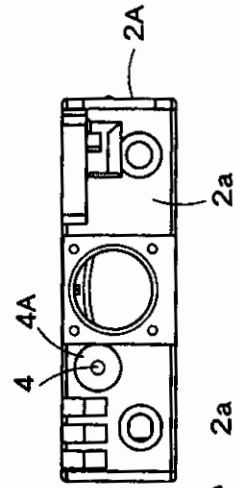


FIG. 6A

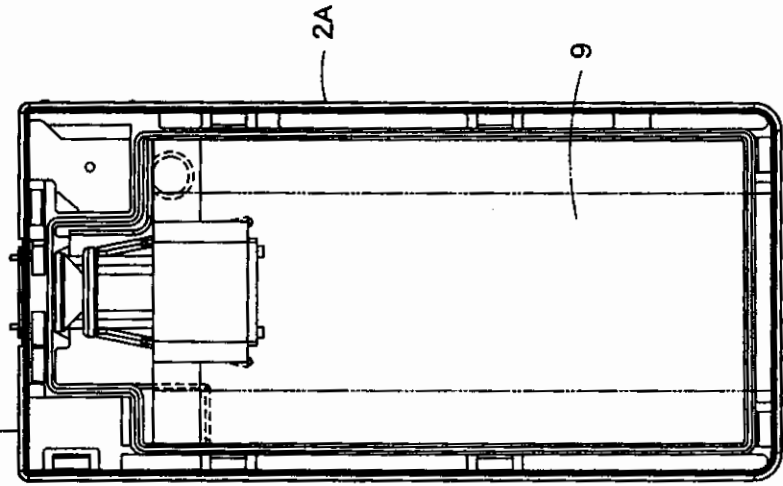


FIG. 6C

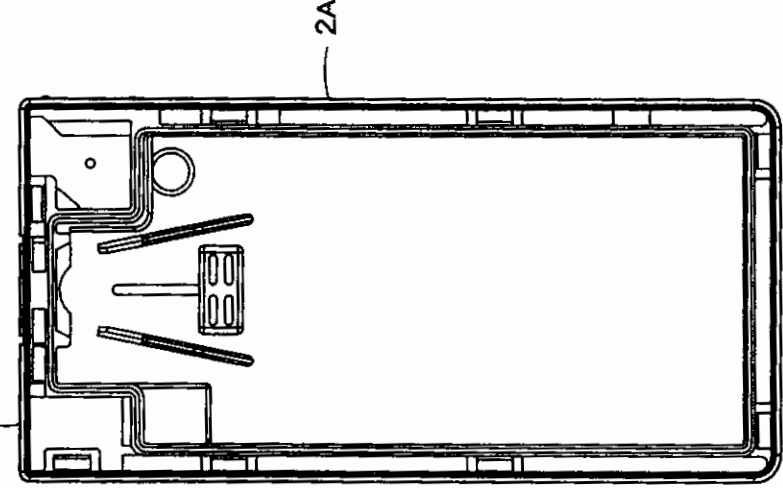
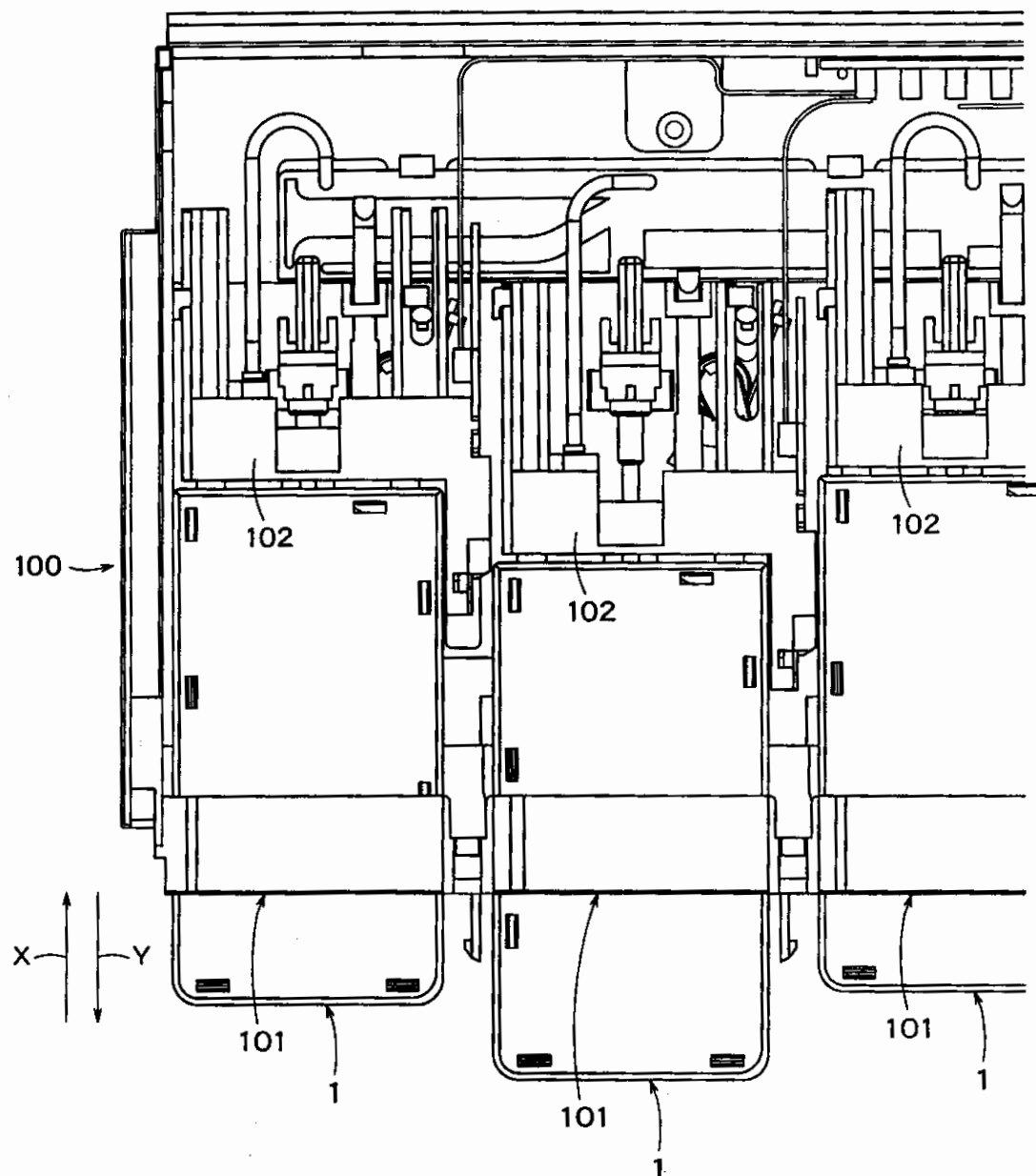
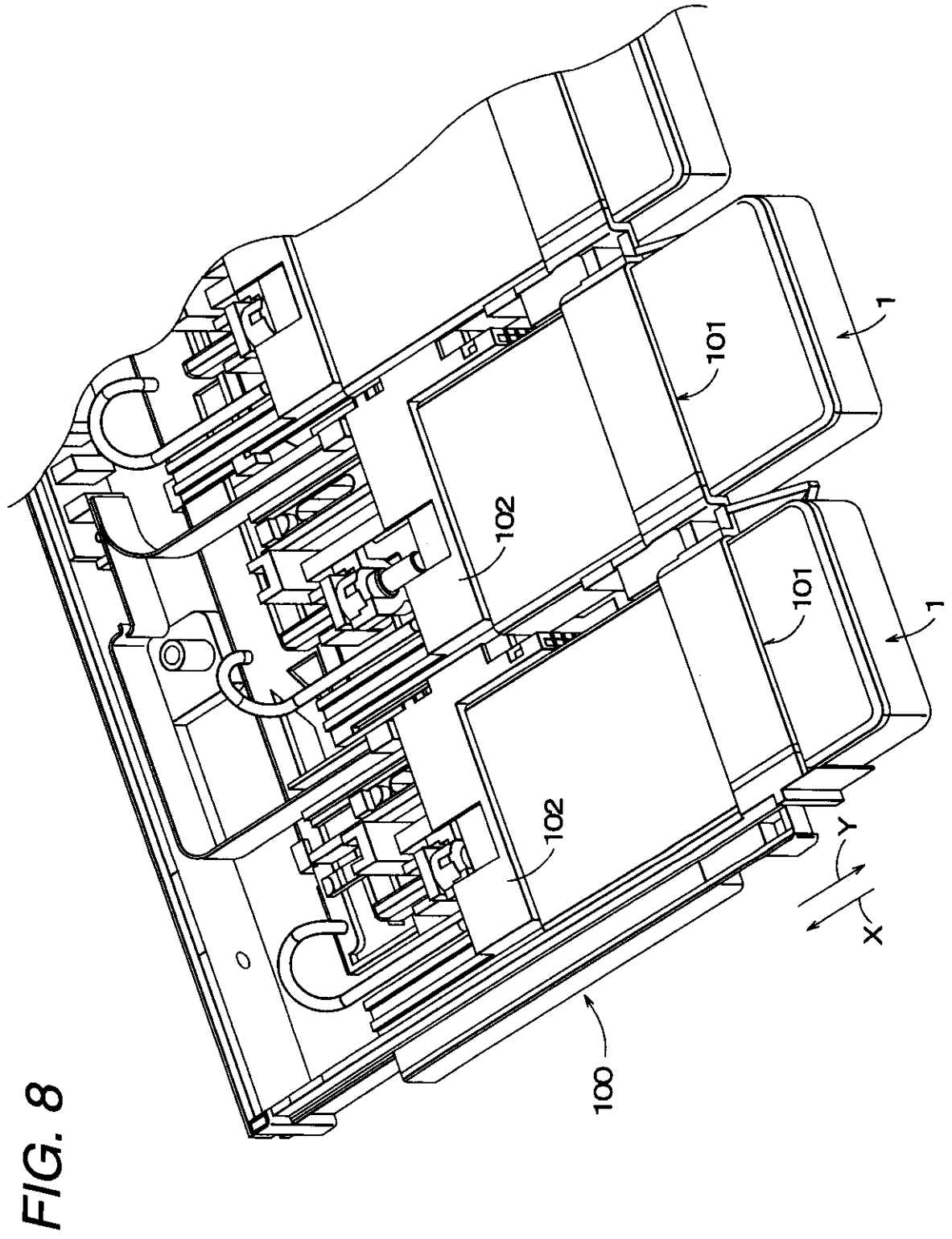


FIG. 7





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FIG. 9

FIG. 9 is a cross-sectional view of a multi-channel electronic device assembly. The assembly includes a base (101) with multiple channels. Each channel contains a component (102) mounted on a substrate (103a, 103b). A component (105) is also present in each channel. A component (104a) is located between the channels, and a component (104b) is located on the side. A component (113) is located above the channels, and a component (114) is located below the channels. The entire assembly is housed within a casing (100).

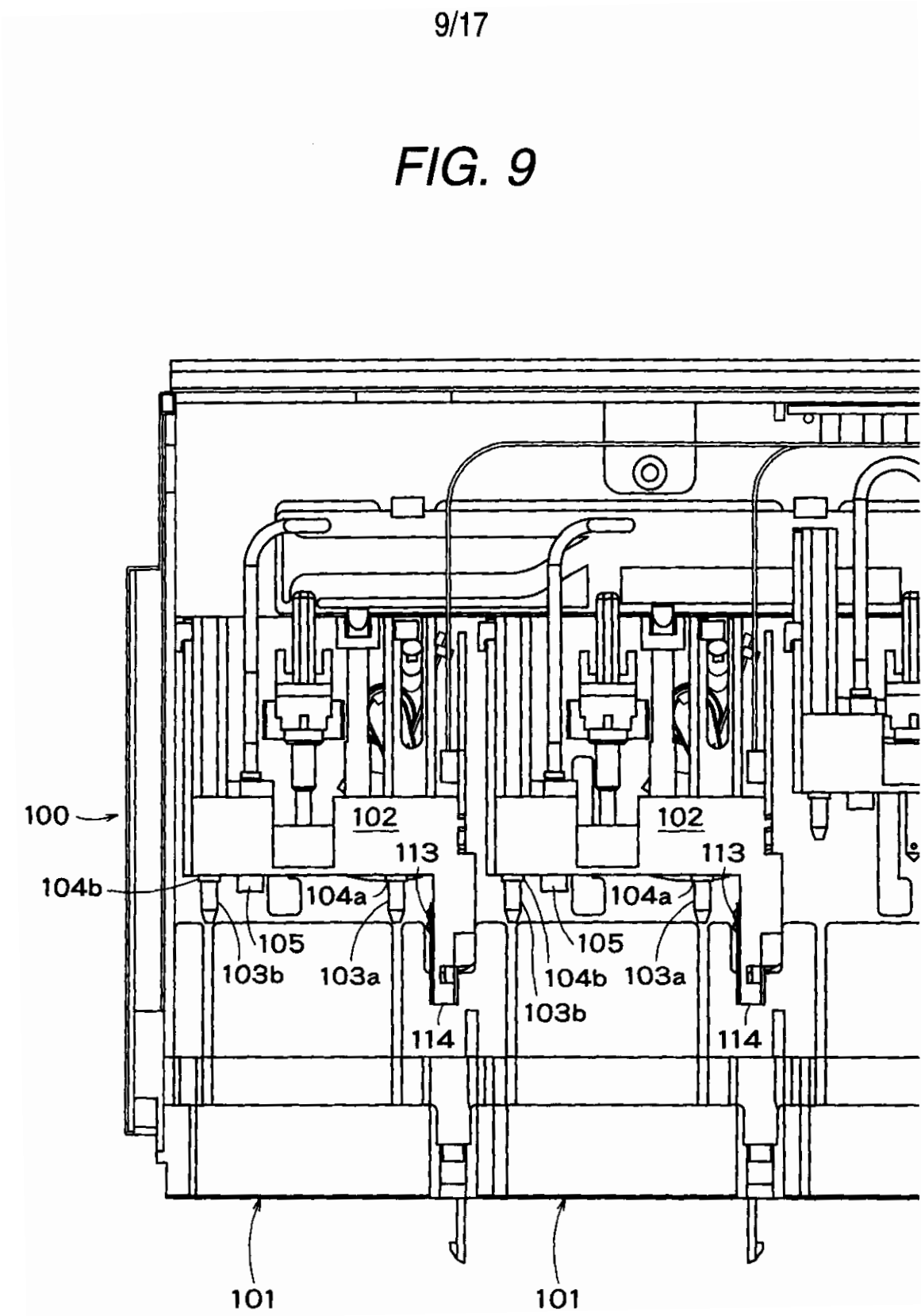


FIG. 10

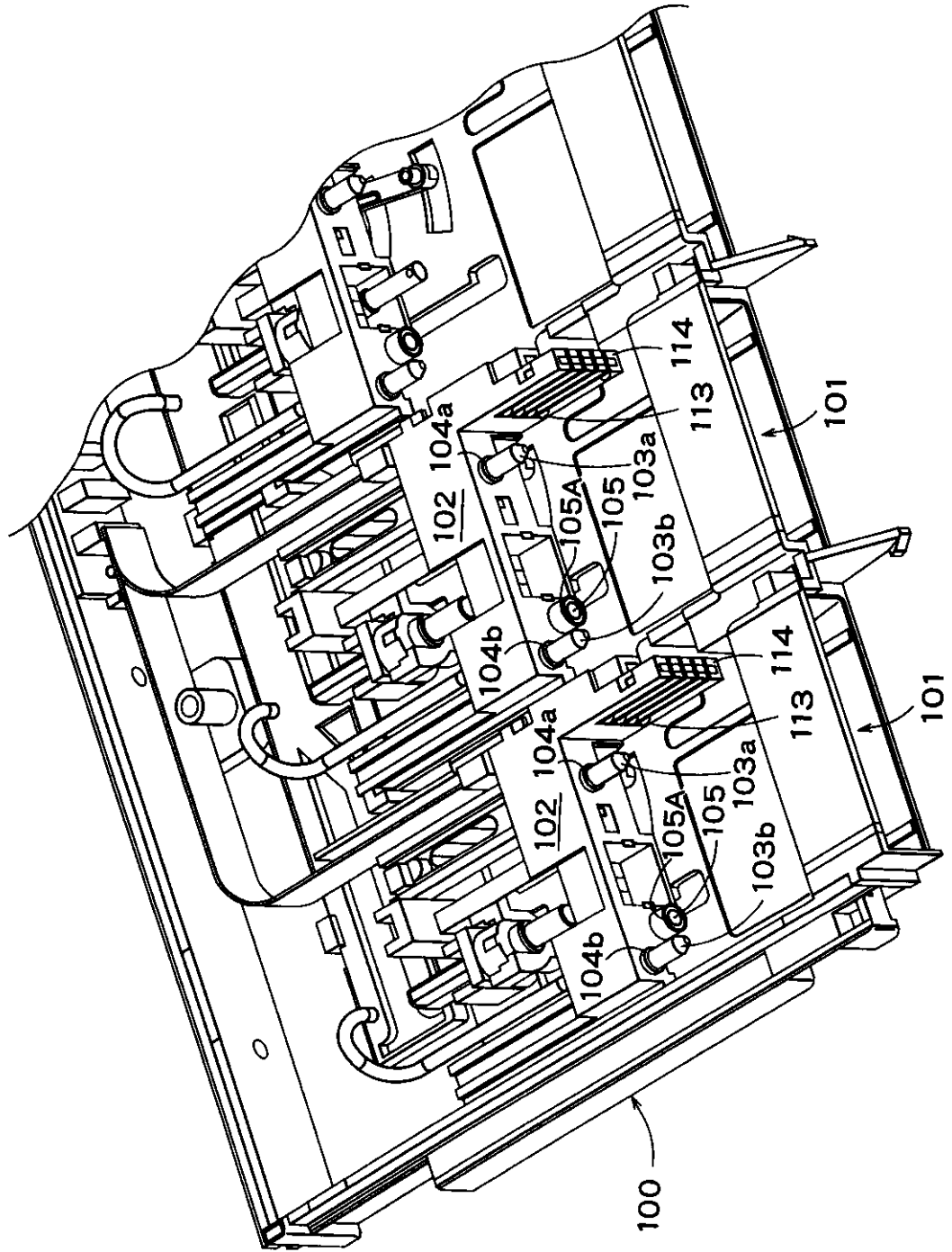


FIG. 11B

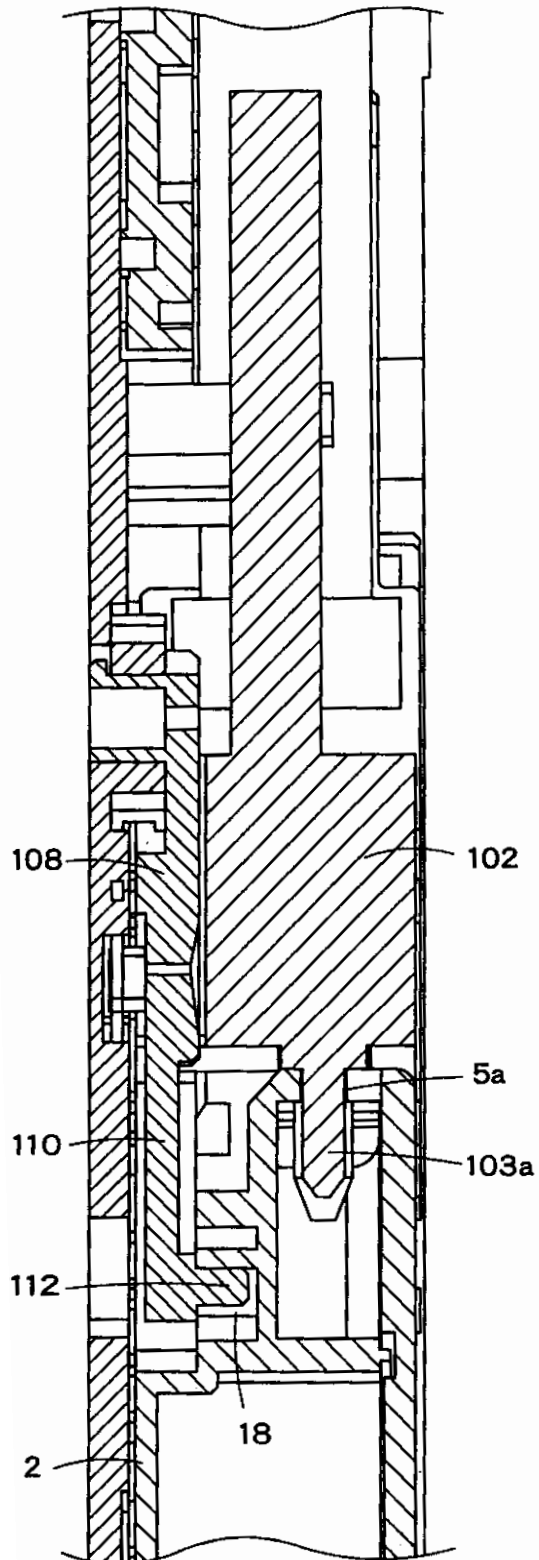


FIG. 11A

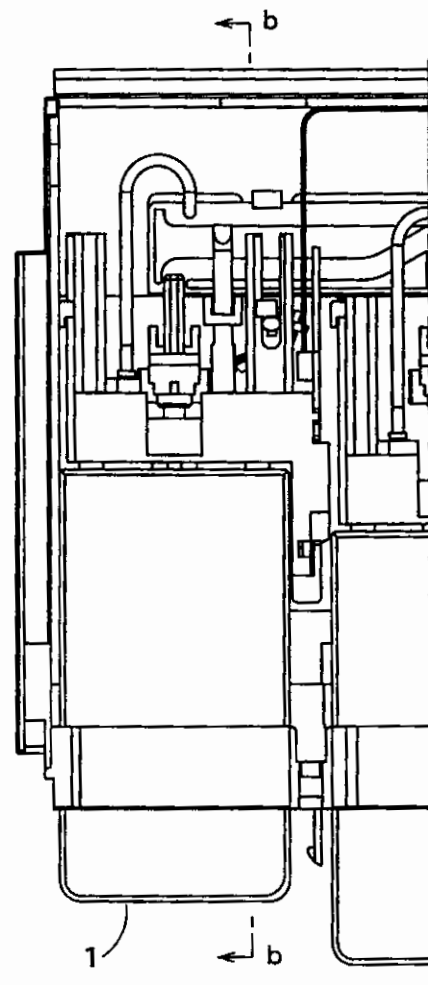


FIG. 12

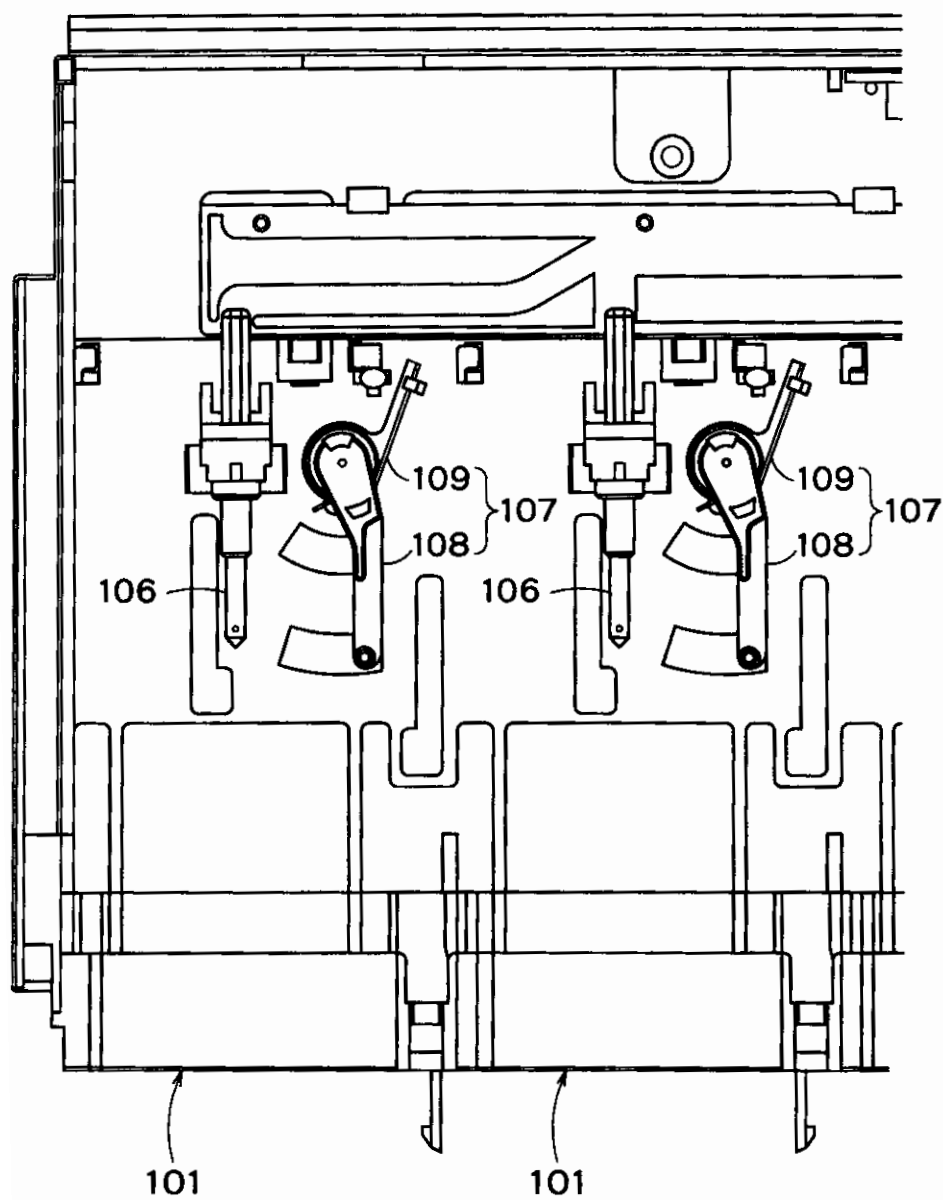


FIG. 13

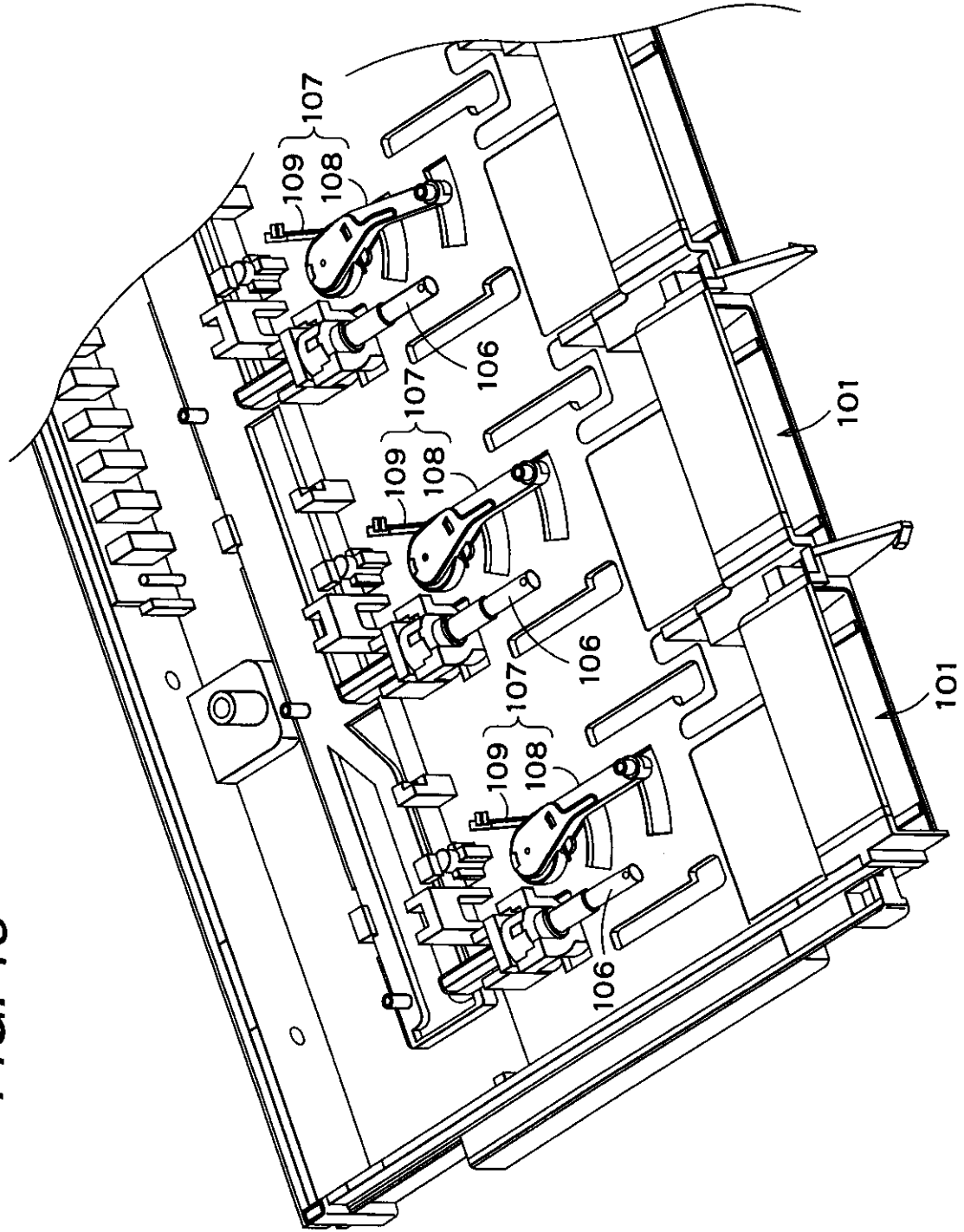


FIG. 14A

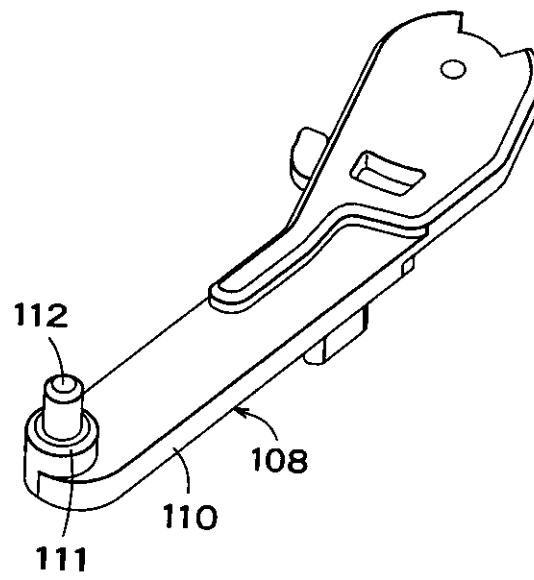


FIG. 14B

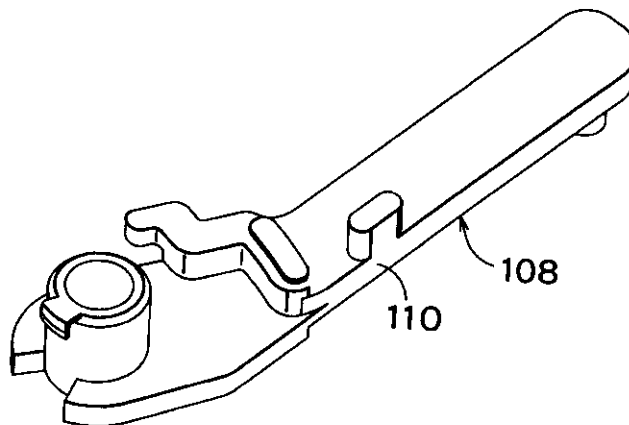


FIG. 15A

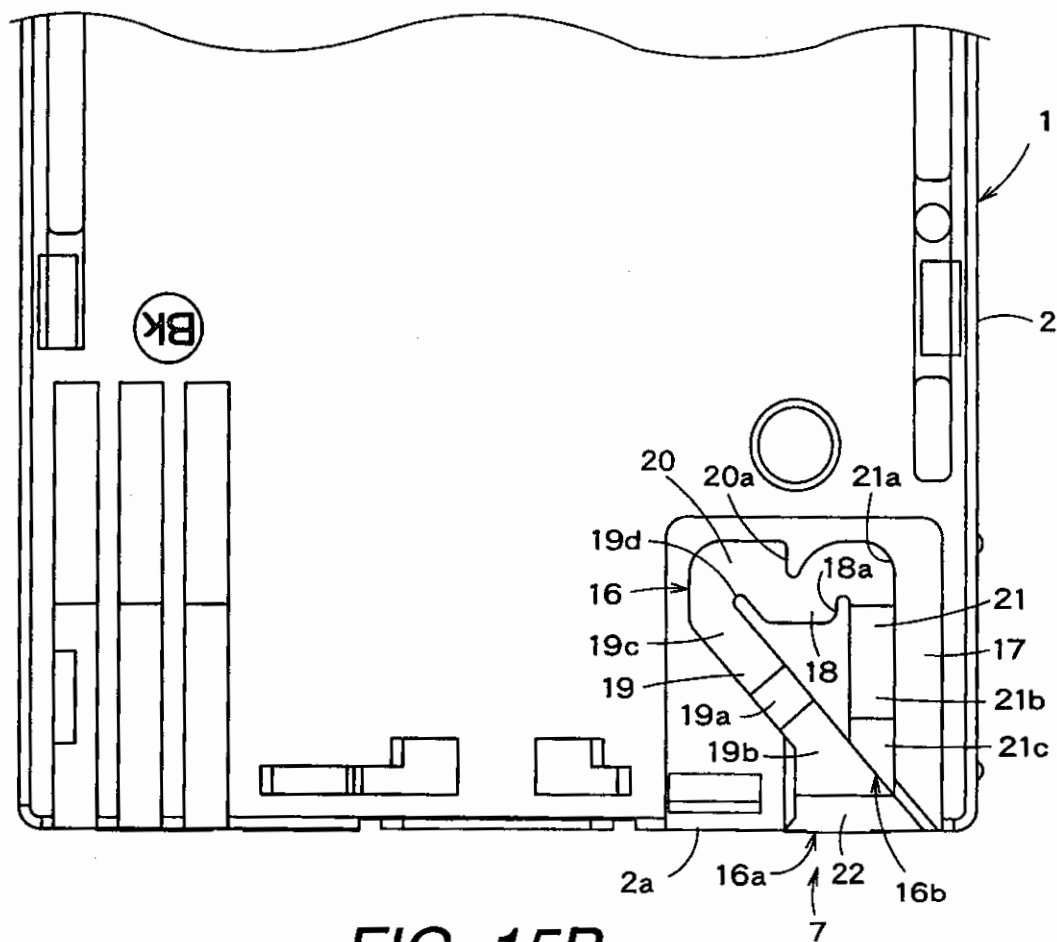


FIG. 15B

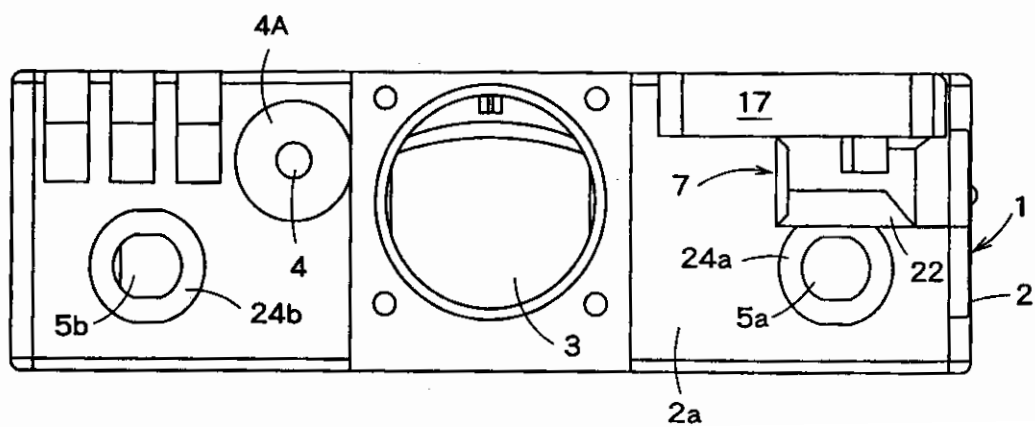


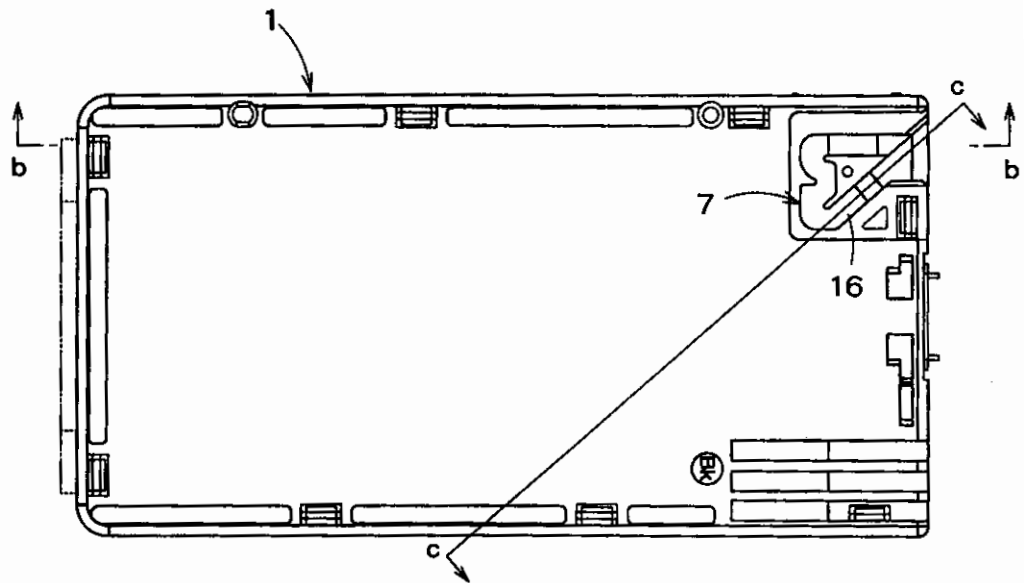
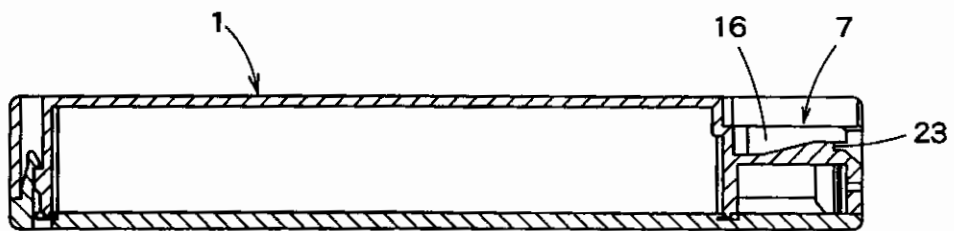
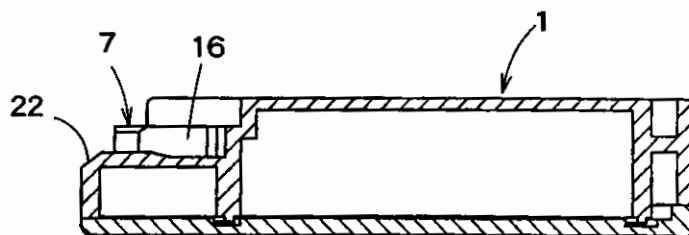
FIG. 16A**FIG. 16B****FIG. 16C**

FIG. 17

